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***Reliability, Packaging, Testing, and
Characterization of MEMS/MOEMS
and Nanodevices IX***

**Richard C. Kullberg
Rajeshuni Ramesham**
Editors

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Introduction

The reliability, packaging, testing, and characterization of MEMS/MOEMS are of paramount importance to the commercialization of these advanced and useful emerging technologies. Contributors to this conference attend from around the world, making it the premier international reliability conference for MEMS/MOEMS. The main objective of this conference is to provide a technical forum for in-depth investigations and interdisciplinary discussions involving reliability, packaging, testing, and characterization of MEMS/MOEMS. The response to the call for papers has been incredible over the years and technically rewarding to the MEMS/MOEMS and associated communities.

The Reliability, Packaging, Testing, and Characterization of MEMS/MOEMS and Nanodevices conference is sponsored by SPIE, and was organized as a part of Photonics West 2010. SPIE is the leading international forum for presentation of the latest developments associated with MEMS and MOEMS including reliability, testing, packaging, materials, surfaces, and characterization. Our conference was part of the Devices/Applications/Reliability symposium track and education program on MOEMS-MEMS held 24–29 January 2010 at Moscone Center, San Francisco, California, USA. This conference has been held for over 10 consecutive years in various forms through the SPIE.

In preparing for the conference, 36 high-quality papers were received from various countries. This year six sessions covered MEMS Packaging: Hermeticity Characterization, Reliability and RF MEMS, Packaging and MEMS Reliability, MEMS Testing and Inspection, MEMS Applications, and Mechanical Properties of materials of MEMS. Our final technical program had three plenary speakers and six invited/keynote speakers from various reputed laboratories around the country and the globe.

We would like to personally thank Dr. Leslie Phinney, Dr. Danelle Tanner, Dr. Sonia García-Blanco, Dr. Allyson Hartzell, Ms. Alyssa M. Fitzgerald, and Dr. Thomas Suleski and Dr. Herald Schenk (symposium chair and cochair), as well as the SPIE staff for their unstinted timely support and encouragement. Finally, we would like to thank all the session chairs and cochairs, and the program committee members for their support in organizing this conference successfully and reviewing the abstract and proceedings articles. We thank all the participants and everyone who participated in this conference.

Richard C. Kullberg
Rajeshuni Ramesham